# US1A THRU US1M

# SURFACE MOUNT ULTRAFAST RECOVERY RECTIFIER

# REVERSE VOLTAGE: FORWARD CURRENT:

## 50 to 1000 VOLTS 1.0 AMPERE

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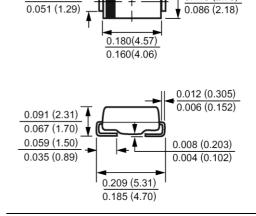
0.110 (2.79)



- · For surface mounted applications
- · Low profile package
- · Built-in strain relief
- · Easy pick and place
- · Ultrafast recovery times for high efficiency
- · Plastic package has Underwriters Laboratory
- Flammability Classification 94V-O
- $\cdot$  High temperature soldering : 260°C /10 seconds at terminals

#### MECHANICAL DATA

Case: Molded plastic, DO-214AC(SMA) Terminals: Solder plated, solderable per MIL-STD-750, method 2026 guaranteed Polarity: Color band denotes cathode end Packaging: 12mm tape per EIA STD RS-481 Weight: 0.002 ounce, 0.064 gram



DO214-AC(SMA)

0.067 (1.70)

Dimensions in inches and (millimeters)

# Maximum Ratings and Electrical Characteristics

Ratings at 25 ambient temperature unless otherwise specified. Single phase, half wave,  $60H_Z$ , resistive or inductive load. For capacitive load, derate current by 20%.

	Symbols	US1A	US1B	US1D	US1G	US1J	US1K	US1M	Units
Maximum Recurrent Peak Reverse Voltage	V <sub>RRM</sub>	50	100	200	400	600	800	1000	Volts
Maximum RMS Voltage	V <sub>RMS</sub>	35	70	140	280	420	560	700	Volts
Maximum DC Blocking Voltage	V <sub>DC</sub>	50	100	200	400	600	800	1000	Volts
Maximum Average Forward Rectified Current at T <sub>L</sub> =100	I <sub>(AV)</sub>				1.0				Amp
Peak Forward Surge Current,									
8.3ms single half-sine-wave	I <sub>FSM</sub> 30							Amp	
superimposed on rated load (JEDEC method)									
Maximum Forward Voltage at 1.0A	V <sub>F</sub>		1.0		1.3		1.7		Volts
Maximum Reverse Currentat $T_A=25$ at Rated DC Blocking Voltage $T_A=100$	I <sub>R</sub>	5.0 100							μАтр
Typical Junction Capacitance (Note 1)	CJ	17							pF
Typical Thermal Resistance (Note 2)	$R_{\theta JL}$	30							/ <b>W</b>
Maximum Reverse Recovery Time (Note 3)	T <sub>RR</sub>	50 75					nS		
Operating Junction Temperature Range	T <sub>J</sub>	-55 to +150							
Storage Temperature Range	Tstg	-55 to +150							

#### NOTES:

1- Measured at 1  $\ensuremath{\text{MH}}_{Z}$  and applied reverse voltage of 4.0 VDC.

2- Thermal resistance from junction to lead mounted on P.C.B. with 0.3 x 0.3" (8.0 x 8.0mm) copper pad areas

3- Reverse Recovery Test Conditions :  $I_{F} \!\!=\! .5A$  ,  $I_{R} \!\!=\! 1A$  ,  $I_{RR} \!\!=\! .25A.$ 



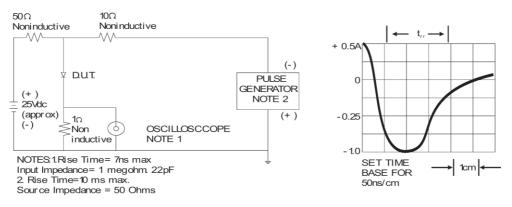
# RATINGS AND CHARACTERISTIC CURVES

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### RATING AND CHARACTERISTIC CURVES



#### Fig. 1-REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM

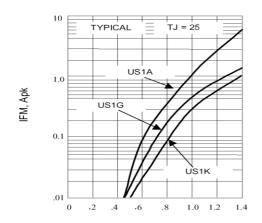


Fig. 2-FORWARD CHARACTERISTICS

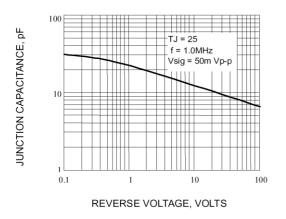
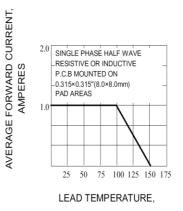


Fig. 4-TYPICAL JUNCTION CAPACITANCE



#### Fig. 3-FORWARD CURRENT DERATING CURVE

